

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

| | | |
|----------------------|---|--|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | | ADG/18/10745 |
| 1.3 Title of PCN | | Additional assembly and test line qualification for FERD diodes housed in DPAK package |
| 1.4 Product Category | | FERD diodes in DPAK package |
| 1.5 Issue date | | 2018-02-20 |

2. PCN Team

| | |
|---------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Richard RENARD |
| 2.1.2 Marketing Manager | Franck DUCLOS |
| 2.1.3 Quality Manager | Jean-Paul REBRASSE |

3. Change

| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
|--------------|--------------------|-------------------------------|
| Machines | (Not Defined) | subco in China (location A+B) |

4. Description of change

| | Old | New |
|--|--------------------------------------|--|
| 4.1 Description | back-end subco in China (location A) | back-end subco in China (location A) back-end subco in China (location B) |
| 4.2 Anticipated Impact on form, fit, function, quality, reliability or processability? | no | |

5. Reason / motivation for change

| | |
|----------------------|--------------------------------------|
| 5.1 Motivation | investment on FERD capacity increase |
| 5.2 Customer Benefit | CAPACITY INCREASE |

6. Marking of parts / traceability of change

| | |
|-----------------|------------------------------------|
| 6.1 Description | internal codification, trace code. |
|-----------------|------------------------------------|

7. Timing / schedule

| | |
|-------------------------------------|--------------|
| 7.1 Date of qualification results | 2018-02-19 |
| 7.2 Intended start of delivery | 2018-05-21 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | |
|--|-------------|
| 8.1 Description | |
| 8.2 Qualification report and qualification results | In progress |

9. Attachments (additional documentations)

10745 Public product.pdf
10745 PCN_DPAK_VF.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | FERD15S50SB-TR | |
| | FERD20H100SB-TR | |
| | FERD20S100SB-TR | |
| | FERD30H100SB-TR | |

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